

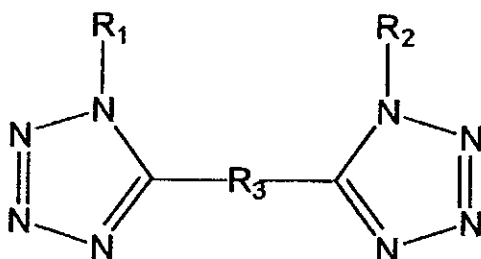
SURFACE-TREATING AGENT FOR METAL

ABSTRACT

A problem for the present invention is to provide a surface-treating agent which improves heat resistance, adhesiveness to resin and solder wettability.

This problem is solved by a surface-treating agent for metal comprising a tetrazole derivative represented by the following general formula and/or a salt thereof.

[Chemical Formula 1]



(wherein R_1 and R_2 each independently represent a hydrogen atom, a halogen atom, or an alkyl group or an aryl group, etc., which each have a carbon number of not more than 10, and a group having a halogen atom, a hydroxyl group, a carboxyl group, an amino group or a mercapto group added thereto, or represent an amino group, a mercapto group, a hydroxyl group or a carboxyl group; and R_3 represents a bond or an alkylene group, etc., which each have a carbon number of not more than 10, and a group having a halogen atom, a hydroxyl group, a carboxyl group, an amino group, a mercapto group, an azo group ($-N=N-$), a sulfide group ($-S-$), or a disulfide group ($-S-S-$) added thereto, or represents an azo group, a sulfide group, or disulfide group).

The surface-treating agent may contain a metal or metal compound.